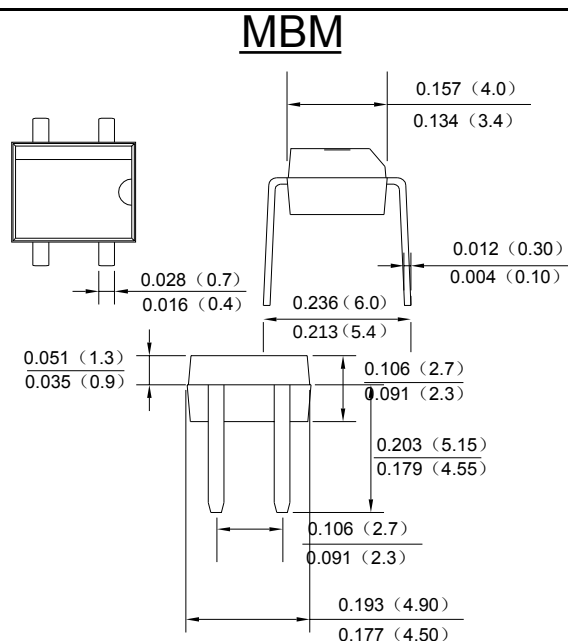


Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	RMB1M	RMB2M	RMB4M	RMB6M	RMB8M	RMB10M	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM}	100	200	400	600	800	1000	V
	V _{RWM}							
	V _{DC}							
RMS Reverse Voltage	V _{RMS}	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T _A =40℃ (Note 2)@T _A =40℃	I _O	0.5 0.8						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30						A
Forward Voltage per element @I _F =0.8A	V _{FM}	1.3						V
Peak Reverse Current @T _A =25℃ At Rated DC Blocking Voltage @T _A =125℃	I _R	5.0 500						uA
Maximum reverse recovery time (Note 3)	T _{RR}	150			250	500		ns
Typical Junction Capacitance per leg	C _J	13						pF
Typical Thermal Resistance per leg (Note 4)	R _{θJA}	70						℃/W
	R _{θJL}	20						
Operating and Storage Temperature Range	T _J , T _{STG}	-55to+150						℃

Note:1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.

3. Reverse Recovery Test Conditions: $I_F=0.5A$, $I_R=1A$, $I_{rr}=0.25A$.

4. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

RMB1M THRU RMB10M

